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# $SiO_2$ assisted $Cu^0-Cu^+-NH_2$ composite interfaces for efficient $CO_2$ electroreduction to $C_{2+}$ products†

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The electrochemical  $CO_2$  reduction reaction ( $CO_2RR$ ) for high value-added multi-carbon product ( $C_{2+}$ ) production over copper oxide-based catalysts is an important way to realize the carbon cycle. However, developing effective reaction interfaces and microenvironments to improve the Faraday efficiency (FE) and current density of  $C_{2+}$  remains a major challenge. Herein, we construct  $Cu^0 - Cu^+ - NH_2$  composite interfaces with the assistance of SiO<sub>2</sub>. Using Cu<sub>2</sub>O nanoparticles as a model catalyst, a layer of porous SiO<sub>2</sub> is first coated on the surface of the particles, and then, a silane coupling agent containing -NH<sub>2</sub> is bonded on the surface of SiO<sub>2</sub>. The strong interaction between SiO<sub>2</sub> and Cu<sub>2</sub>O at the interface induces the oxidation effect of low valent Cu, and even under the CO<sub>2</sub>RR, part of Cu<sup>+</sup> is reduced to Cu<sup>0</sup> and part of Cu<sup>+</sup> still maintains positive valence, forming the interface of Cu<sup>0</sup>-Cu<sup>+</sup>. SiO<sub>2</sub> also acts as a bridge between copper species and -NH2 to create a Cu catalyst-NH2 group interface. With the help of the synergistic effect of the composite interfaces, the optimized Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst achieves a FE of 81.2% for  $C_{2+}$  products with a current density of 292 mA cm<sup>-2</sup> at -1.7 V versus a reversible hydrogen electrode. In situ Raman and attenuate total reflectance-infrared absorption spectroscopy spectra show that the interaction between surface -NH2 and CO2 molecules enhances the adsorption and activation process of  $CO_2$  and promotes the formation of CO intermediates (\*CO). On the  $Cu^0-Cu^+$  interface, the C-C coupling process between \*CO is accelerated, and the two interfaces synergistically promote the generation of C2+ products. This work provides a new strategy for constructing composite interfaces to improve the CO<sub>2</sub>RR to C<sub>2+</sub> products

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## 1. Introduction

The excessive emission of CO<sub>2</sub> breaks the balance of the natural carbon cycle; therefore, it is urgent to develop new technologies for CO<sub>2</sub> recycling and utilization to realize the sustainable development of resources and energy, and mitigate global warming. The electrochemical CO<sub>2</sub> reduction reaction (CO<sub>2</sub>RR) coupled with renewable electric energy can not only synthesize high-value-added products from CO<sub>2</sub> but also realize energy

storage at the same time, which is a promising way of CO<sub>2</sub> utilization.<sup>2,3</sup> Up to now, it has been reported that at least 16 distinct products are formed from the CO<sub>2</sub>RR, such as CO, CH<sub>4</sub>, HCOOH, C<sub>2</sub>H<sub>4</sub>, C<sub>2</sub>H<sub>5</sub>OH, C<sub>3</sub>H<sub>7</sub>OH, and so on.<sup>4,5</sup> Among the CO2RR products, C2+ can be used as a chemical raw material and fuel, leading to wide application.1,6 Consequently, researchers have made significant endeavors in the synthesis of C<sub>2+</sub> through the CO<sub>2</sub>RR. However, CO<sub>2</sub> is a linear and inert molecule with a C=O bond energy of up to 750 kJ mol $^{-1}$ . Thus, achieving C=O activation under milder conditions requires the use of appropriate catalysts. Currently reported catalysts for CO<sub>2</sub>RR synthesis of C<sub>2+</sub> products are mainly Cu-based catalysts, because they have a moderate adsorption strength for C<sub>1</sub> intermediates in the CO<sub>2</sub>RR process, which is neither too strong for desorption nor too weak for further adsorption activation for subsequent reactions, to promote the dimerization between C<sub>1</sub> intermediates and generate C2+ products.1,8

Among Cu-based catalysts, the oxides of Cu and their derivatives are an important type of catalyst with high reactivity. Puring the reduction and reconstruction process, abundant metal-oxide (Cu<sup>0</sup>-Cu<sup>ô+</sup>) interfaces are generated for Cu oxides, which significantly enhance the activity of the catalysts and improve the rate of C-C coupling. Therefore, their

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electronic structure13 and morphology14,15 have been widely studied to improve the activity of the CO<sub>2</sub>RR to C<sub>2+</sub> products. Especially, recent studies have found that the adsorption strength of the CO intermediate (\*CO) on  $Cu^{\delta+}$  species (0 <  $\delta$  < 2) is stronger than that on Cu<sup>0</sup> species at the metal-oxide interface, 16-18 which is beneficial to increase the concentration of \*CO on the catalyst surface and promote the \*CO dimerization step. Therefore, it is important to improve the stability of  $Cu^{\delta^+}$  species under reduction conditions to produce  $C_{2^+}$  products. For example, Zhou et al. 16 reported a B-doped Cu catalyst to regulate the local electronic structure of Cu and improve the stability of positive valence Cu. Consequently, the adsorption and dimerization of \*CO can be controlled by adjusting the average oxidation valence of Cu, which makes the Cu(B) catalyst achieve 79% faradaic efficiency (FE) of C<sub>2</sub> in the CO<sub>2</sub>RR process. In addition, Yan et al.19 reported a hexagonal boron nitride (h-BN) modified Cu<sub>2</sub>O catalyst, where the strong electron interaction between the two components of Cu2O and BN makes the electrons on Cu<sub>2</sub>O transfer to BN to strengthen the Cu-O bond, thus stabilizing the Cu<sup>+</sup> species during the CO<sub>2</sub>RR. Upon applying the Cu<sub>2</sub>O-BN catalyst for the CO<sub>2</sub>RR process, the ratio of C<sub>2</sub>H<sub>4</sub>/CO increased by 1.62 times compared with that of the Cu<sub>2</sub>O catalyst. Similarly, Zang et al.<sup>20</sup> designed a carbon-coated CuO<sub>x</sub> (CuO<sub>x</sub>@C) catalyst and the carbon layer on the catalyst surface effectively stabilized Cu<sup>+</sup> species, thereby facilitating the C-C coupling process. In the CO<sub>2</sub>RR process, the FE of ethanol reached 46%, and the partial current density reached 166 mA cm<sup>-2</sup>. A series of studies have proven that the interfaces between Cu<sup>+</sup> and Cu<sup>0</sup> regions could promote C<sub>2+</sub> production. Additionally, organic molecules containing amino groups (-NH<sub>2</sub>) are often used as surface modifiers to regulate the surface properties of catalysts, thereby altering the reaction microenvironment during the CO2RR. Li et al.21 constructed a molecular-catalyst interface by modifying a layer of an N-aryldihydropyridine-based oligomer on the surface of the Cu catalyst, which made the catalyst exhibit excellent ethylene selectivity with an FE of 72% at -0.83 V versus the reversible hydrogen electrode (vs. RHE; the same potential scale is used in the following discussion unless otherwise specified) during the CO<sub>2</sub>RR. Similarly, Chen et al.<sup>22</sup> incorporated polyamine on Cu electrodes. Due to the strong binding force between the CO2/CO molecule and -NH2, the polyamine-Cu interface formed a microenvironment with locally high concentrations of CO2 and CO, which accelerates the formation of ethylene and the FE reached 72% at -0.97 V. According to the above discussion, the Cu<sup>0</sup>-Cu<sup>+</sup> reaction interface and -NH<sub>2</sub> induced molecular-catalyst interface both can promote the formation of C<sub>2+</sub> products in the CO2RR.

The widely suggested  $CO_2$ -to- $C_{2+}$  conversion mechanisms show that the promoted CO<sub>2</sub> activation, the faster formation and adsorption of the C<sub>1</sub> intermediate, and the accelerated C-C coupling process are essential to increase the selectivity of C<sub>2+</sub> products. However, developing a reaction interface that simultaneously meets the requirements of three aspects still faces great challenges. In this work, we construct a Cu<sup>0</sup>-Cu<sup>+</sup>-NH<sub>2</sub> composite reaction interface with the assistance of SiO2, which includes both the Cu-based Cu<sup>0</sup>-Cu<sup>+</sup> interface and the Cu

catalyst-NH2 group interface. We have fully utilized two characteristics of amorphous SiO2: firstly, it can uniformly coat inorganic nanoparticles, and secondly, it can bond with silane coupling agents to introduce organic functional groups. Using Cu<sub>2</sub>O nanoparticles as a model catalyst, a layer of porous SiO<sub>2</sub> is first coated on the surface of the particles (named Cu<sub>2</sub>O@SiO<sub>2</sub>). Under the conditions of electrochemical reduction, part of Cu<sup>+</sup> is reduced to Cu<sup>0</sup>, and part of Cu<sup>+</sup> maintains positive valence under the strong interaction of SiO2, forming the interface of Cu<sup>0</sup>-Cu<sup>+</sup>. Then, a silane coupling agent containing -NH<sub>2</sub> is bonded on the surface of SiO<sub>2</sub> (named Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub>), and the SiO2 coating acts as a bridge between copper species and -NH<sub>2</sub> to form a Cu catalyst-NH<sub>2</sub> group interface. With the help of the synergistic effect of the Cu<sup>0</sup>-Cu<sup>+</sup>-NH<sub>2</sub> composite interfaces, the optimized Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst achieves a selectivity of 81.2% for  $C_{2+}$  products at a current density of 292 mA cm<sup>-2</sup> at -1.7 V (without iR compensation). *In situ* Raman and attenuate total reflectance-infrared absorption spectroscopy (ATR-IRAS) spectra show that the interaction between surface -NH2 and CO<sub>2</sub> molecules enhances the adsorption and activation process of CO2 and promotes the formation of \*CO, which increases the local concentration of surface \*CO. On the Cu<sup>0</sup>-Cu<sup>+</sup> interface, the C-C coupling process between \*CO is accelerated, and the two interfaces synergistically promote the generation of C2+ products. This work provides a new strategy for constructing composite interfaces to promote the CO2RR to C2+ product conversion under high current density.

#### 2. Experimental section

## 2.1 Materials

All reagents involved in this study were commercially available and used without further purification: CuCl<sub>2</sub>·2H<sub>2</sub>O (AR, Jiang-Tian), NaOH (AR, MACKLIN), Na<sub>2</sub>CO<sub>3</sub> (AR, JiangTian), KCl (AR, JiangTian), ethyl orthosilicate (GC, Aladdin), aminopropyl triethoxysilane (AR, HEOWNS), ascorbic acid (AR, JiangTian), noctane (AR, MERYER), 1-arginine (AR, JiangTian), polyvinylpyrrolidone (MW = 58 000, MACKLIN). All aqueous solutions were prepared with deionized water. A proton exchange membrane (Nafion 211, DuPont), Nafion (5 wt%, Sigma-Aldrich), isopropanol (>99%, Aladdin), carbon NPs (50 nm, Sigma-Aldrich), and graphite (Aladdin) were obtained.

## 2.2 Catalyst preparation

Cu<sub>2</sub>O dodecahedron nanoparticles were synthesized by a method reported in the literature.23 1.11 g PVP was dissolved into deionized water, and then 10 mL of 0.1 mol L-1 CuCl2-·2H<sub>2</sub>O was also added into the above solution dropwise, under stirring and heating to 55 °C. Then 10 mL of 2 mol L<sup>-1</sup> NaOH solution was added. After stirring at 55 °C for 30 min, 10 mL of 1 mol L-1 ascorbic acid solution was added to the mixture and continued to stir at 55 °C for 3 h. Then, the precipitation was centrifuged and washed in deionized water and anhydrous ethanol 3 times to obtain Cu<sub>2</sub>O dodecahedron nanoparticles.

Then the Cu2O nanoparticles were modified with SiO2 and -NH<sub>2</sub>.<sup>24</sup> 0.73 g n-octane and 0.014 g L-arginine were added into 15 mL deionized water and stirred vigorously at 60 °C. n-Octane was used as the solvent to prevent excessive polymerization of SiO<sub>2</sub>, and to control the formation process of SiO<sub>2</sub> on the surface of Cu<sub>2</sub>O. After that, 25 μL ethyl orthosilicate (TEOS) was added to the mixture and stirred at 60 °C for 4 h. Then 0.2 g Cu<sub>2</sub>O dodecahedron nanoparticles were added into the mixture and stirred at room temperature for 20 h. The precipitation was centrifuged and washed three times with deionized water and anhydrous ethanol to obtain Cu2O@SiO2 nanoparticles. The obtained Cu2O@SiO2 nanoparticles were evenly dispersed into 25 mL anhydrous ethanol, and then 25 μL aminopropyl triethoxysilane (APTES) was added, and stirred at room temperature for 24 h. The precipitation was centrifuged, washed three times with anhydrous ethanol and deionized water, and dried by vacuum at room temperature for 12 h. Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> nanoparticles were obtained. For the control sample of Cu<sub>2</sub>-O@SiO<sub>2</sub>, the amount of TEOS was increased to 50 μL during the SiO<sub>2</sub> coating process to maintain a coating thickness similar to that of the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> sample.

## 2.3 Catalyst characterization

Scanning electron microscopy (SEM) images were obtained on a Hitachi S-4800 field emission scanning electron microscopy. Transmission electron microscopy (TEM) and high-angle annular dark-field scanning transmission electron microscopy (HAADF-STEM) were conducted on a JEOL F200 transmission electron microscope with an acceleration voltage of 200 kV. The samples were dispersed in ethanol and ultrasonically treated for 20 min, and then the samples were added dropwise onto a Mo grid ultrathin carbon film. X-ray diffraction was conducted on a Bruker D8 Focus X-ray diffractometer using Cu Kα radiation (λ = 0.15418 nm). The tube voltage and current were 40 kV and 40 mA, respectively. The diffraction angle of samples was recorded from 20° to 80° (2 $\theta$ ) with a scan rate of 5° min<sup>-1</sup>. N<sub>2</sub> physisorption analysis was conducted at −196 °C using a Tristar 3000 Micromeritics instrument. XPS was conducted on a Thermo-Fisher Scientistic K-Alpha+ instrument. The X-ray radiation source was Al K $\alpha$  ( $h\nu = 1486.6$  eV) with an X-ray power of 150 W and the spot size was 400 µm. The pass energy was 50 eV. The XPS was calibrated with a C 1s binding energy of 284.8 eV. X-ray absorption fine structure (XAFS) measurements were performed to probe the valence state and the bonding information of Cu species on a TableXAFS-500 Xray absorption fine structure spectrometer. The CO2 adsorption experiment was carried out on a BEL SORP-max at 298 K.

## 2.4 Electrode preparation

We first prepared a conductive gas-diffusion layer by sputtering the Cu layer on a PTFE film, copper target (99.999%). To prepare the catalyst ink, 10 mg of the pre-catalyst and 2 mg of carbon were dispersed in a mixture of 1 mL propanol and 30  $\mu L$  of 5 wt% Nafion solution (Sigma-Aldrich); 10 mg carbon was dispersed in a mixture of 1 mL of propanol and 50  $\mu L$  of 5 wt% Nafion solution; 10 mg graphite was dispersed in a mixture of 1 mL of propanol and 70  $\mu L$  of 5 wt% Nafion solution, and then they were sonicated for at least 1 hour. The ink was airbrushed

onto a 2  $\times$  3 cm<sup>2</sup> Cu/PTFE substrate with a loading of  $\sim$ 1 mg cm<sup>-2</sup>; the carbon–graphite mixture was sprayed on the catalyst surface in turn. The PTFE-based gas diffusion electrode could enhance  $CO_2$  gas mass transfer through hydrophobic PTFE channels and the carbon powder and graphite powder with certain hydrophobicity on the surface of the catalyst could tailor the wettability of the electrolyte and prevent the catalyst from being flooded by aqueous electrolyte. A stainless-steel mesh was used as the anode. Before the reaction, the steel (1.5  $\times$  2 cm<sup>2</sup>) was sonicated in acetone and deionized water for 30 min, respectively, and then dried by nitrogen purging for further use.

## 2.5 Electrochemical CO<sub>2</sub> reduction measurement

The CO2RR activity of the catalyst was investigated by performing electrolysis in a flow-cell configuration using 1 M KCl as the cathodic and 2 M KOH as the anodic electrolyte. Clanions can specifically adsorb on the inner Helmholtz plane (IHP) of the catalyst surface, which not only confines CO2 and facilitates electron transfer from the electrode to CO2 via the X<sub>ad</sub>-C bond but also improves the \*CO adsorption for favorable C-C coupling.25 Moreover, the formation of OH during the CO<sub>2</sub>RR in the KCl electrolyte leads to a local alkaline environment, and the use of high pH can greatly accelerate the production rates for C2+ products.26 The flow cell consists of a gas diffusion layer as the working electrode (0.5  $\mathrm{cm}^2$ ), a proton exchange membrane (Nafion 211), a stainless-steel mesh (1500 mesh) as the counter electrode, and Ag/AgCl (saturated KCl) as the reference electrode. An electrochemical workstation (CHI660, Chenhua, Shanghai) was used to perform the CO<sub>2</sub>RR test. CO<sub>2</sub> was supplied into gas chambers with a constant rate of 10 mL min<sup>-1</sup> by using a mass-flow controller, and the outlet gas flow rate was also recorded by the flow controller. The cathodic electrolyte (30 mL) was circulated through the electrolyte chambers under a constant flow (5 mL min<sup>-1</sup>) via a peristaltic pump. The anodic electrolyte was circulated through the anodic chamber by a gas-liquid mixed flow pump. Reactions were tested via chronoamperometry for 30 min at different applied potentials from -1.1 V to -1.9 V. Gas products were analyzed via online GC (Shimadzu 2010) with a Thermal conductivity detector (TCD) (column: Agilent Carbon Plot (30 m × 0.32 mm  $\times$  3  $\mu$ m)). The FE of gas products was calculated based on the following:

$$FE = \frac{C_{\text{product}} \times V_{\text{CO}_2} \times 10^{-3} \times t \times e \times F}{V_m \times O} \times 100\%$$

where  $C_{\rm product}$  is the concentration of the gas-phase products (mol L<sup>-1</sup>),  $\nu_{\rm CO_2}$  is the flow rate of CO<sub>2</sub>, t is the reaction time, e is the number of transferred electrons for the product, F the Faraday constant 96 485 C mol<sup>-1</sup>,  $V_{\rm m}$  is the gas mole volume, and Q is the total quantity of electric charge.

The liquid products were determined by H NMR (JEOL JNM ECZ600R 600 MHz), in which 300  $\mu$ L electrolyte was mixed with 300  $\mu$ L D<sub>2</sub>O and 10  $\mu$ L diluent dimethyl sulfoxide (DMSO), wherein DMSO served as an internal standard. The concentration of liquid products was calculated based on the following:

$$\frac{V_{\rm DMSO} \times \rho_{\rm DMSO} \times 10^{-3}}{\frac{M_{\rm DMSO}}{c_X \times 300 \times 10^{-6} \times n_{X(\rm H)}}} = \frac{1}{N}$$

where V is the volume of DMSO;  $\rho_{\rm DMSO}$  is the density of DMSO (1.1 g cm<sup>-3</sup> at 20 °C); M is the molar mass;  $c_X$  is the concentration of X product;  $n_{X(H)}$  is the number of hydrogen atoms in the product X in the nuclear magnetic spectrum used to calculate the concentration of X;  $\frac{1}{N}$  is the ratio of the product peak area to DMSO area in the nuclear magnetic spectrum.

The FE of liquid products was computed from:

$$FE = e \times F \times n/Q$$

where n is the total product (in moles).

Potentials were referenced to the RHE based on the following:

$$E_{\text{RHE}} = E \text{ (vs. Ag/AgCl)} + 0.197 \text{ V} + 0.059 \times \text{pH}$$

### 2.6 In situ Raman test

In situ Raman experiments were conducted by Confocal Raman Microscopy (Horiba) with a 785 nm near-infrared laser in a homemade electrolyzer cell. A platinum electrode and Ag/AgCl electrode were used as the counter and reference electrodes, respectively. The catalyst for the cathode was sprayed on carbon paper  $(0.5 \times 1 \text{ cm}^2)$  using ionomer solution as a binder. The electrolyte (1 M KCl) was saturated with CO<sub>2</sub> solution and CO<sub>2</sub> was continued to inject at a flow rate of 5 mL min<sup>-1</sup>. A long focal length lens (Leica, 50×) was used for focusing and collecting the incident and scattered laser light. Electrolysis at different cathodic potentials was performed for 10 min before signal collection.

## In situ ATR-IRAS measurement

In situ ATR-IRAS experiments were performed on a Nicolet iS20 spectrometer equipped with a HgCdTe (MCT/A) detector and a VeeMax III (PIKE Technologies) accessory in a homemade single-cell electrolyzer. A platinum electrode and Ag/AgCl electrode were used as the counter and reference electrodes. A fixedangle Si prism (60°) coated with a catalyst embedded into the bottom of the cell served as the working electrode. Before testing, the detector was cooled with liquid nitrogen for at least 30 min to maintain a stable signal. Electrolysis at different cathodic potentials was carried out for 3 min with chronoamperometry by spectrum collection (32 scans, 4 cm<sup>-1</sup> resolution). All spectra were subtracted from the background.

#### 3. Results and discussion

## Synthesis of catalysts and characterization analysis

As shown in Fig. 1, the synthesis of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> can be divided into three steps. Firstly, Cu<sub>2</sub>O dodecahedron nanoparticles were synthesized by a precipitation method. Second, the Cu<sub>2</sub>O NPs were mixed with TEOS uniformly, and the SiO<sub>2</sub>

formed during the hydrolysis of TEOS is uniformly covered on the surface of Cu<sub>2</sub>O NPs to form Cu<sub>2</sub>O@SiO<sub>2</sub> samples. Finally, the Cu<sub>2</sub>O@SiO<sub>2</sub> nanoparticles and ATPES were evenly dispersed with anhydrous ethanol to obtain Cu2O@SiO2-NH2.24 The detailed procedure is discussed in the Experimental section.

The morphology of the catalyst was characterized by SEM. As shown in Fig. 2a-c and S1,† the Cu2O nanoparticles exhibit a regular dodecahedral shape. After SiO<sub>2</sub> coating, the surface of the nanoparticles becomes rough, indicating the successful coating of SiO<sub>2</sub>, and there may be a porous structure (Fig. 2b and S1b†). In the subsequent modification process of -NH<sub>2</sub>, the whole particle still maintained a complete dodecahedral structure. The results show that the SiO<sub>2</sub> coating and -NH<sub>2</sub> modification have no significant effect on the overall structure of Cu<sub>2</sub>O nanoparticles (Fig. 2a-c and S1†). The structure of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH2 and control samples were characterized by TEM. As shown in Fig. S2,† the Cu<sub>2</sub>O nanoparticle exhibits a smooth surface in the TEM image, and the high-resolution TEM (HR-TEM) image shows that there is a lattice fringe d = 0.213 nm on the catalyst surface, which is assigned to the Cu<sub>2</sub>O (200) surface (Fig. S2b†). The Cu and O elements overlap with the STEM image in EDX element mapping (Fig. S2c†). In the TEM images of the Cu<sub>2</sub>-O@SiO<sub>2</sub> sample (Fig. S3a-c†), a lattice fringe of d = 0.246 nm can be seen in the inner layer, which belongs to the Cu<sub>2</sub>O (111) crystal plane, and an amorphous SiO<sub>2</sub> coating with a thickness of about 10 nm located at the outer layer can be seen, which construct the obvious Cu<sub>2</sub>O-SiO<sub>2</sub> interface. At the same time, the STEM and EDX element distribution maps further confirm the formation of the coating structure (Fig. S3d and e†). For the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> sample, a uniform coating layer with a thickness of about 13 nm can be seen on the surface of Cu<sub>2</sub>O nanoparticles (Fig. 2a-f). By comparison with Cu2O@SiO2, it can be preliminarily confirmed that the Cu<sub>2</sub>O@SiO<sub>2</sub> sample surface has been successfully modified with -NH2. The lattice fringe of d = 0.302 nm of the Cu<sub>2</sub>O (110) facet in close contact with the SiO<sub>2</sub>-NH<sub>2</sub> coating layer in HR-TEM images (Fig. 2g) can confirm the formation of a Cu<sub>2</sub>O-SiO<sub>2</sub>-NH<sub>2</sub> interface. Furthermore, the EDX elemental maps show that the Si and N elements are mainly distributed on the surface of Cu<sub>2</sub>O nanoparticles, and the overlay image of element distribution further proves the formation of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub>. The surface pore distribution on the surface of Cu<sub>2</sub>O and Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalysts was characterized by using N2 isothermal adsorption-desorption curves. As illustrated in Fig. S4a,† the surface of Cu<sub>2</sub>O exhibits almost no pore structure. In contrast, the N2 isothermal adsorptiondesorption curve of the Cu2O@SiO2-NH2 catalyst reveals a gradual uptake of nitrogen gas with a hysteresis loop, indicating the presence of irregular pores on its surface. At the same time, combined with the pore size distribution diagram in Fig. S4b,† it shows that there are mesoporous pores with an average pore size of 3.32 nm distributed on the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH2 catalyst surface. And its specific surface area increases from 6 m<sup>2</sup> g<sup>-1</sup> of  $Cu_2O$  to 40 m<sup>2</sup> g<sup>-1</sup> of  $Cu_2O$ @ $SiO_2$ - $NH_2$ .

X-ray diffraction (XRD) was conducted to analyze the chemical compositions of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and the control samples. As shown in Fig. 3a and S5,† five obvious diffraction peaks in the XRD pattern of Cu<sub>2</sub>O are located at  $2\theta = 29^{\circ}$ ,  $36^{\circ}$ ,  $42.5^{\circ}$ ,  $62^{\circ}$ 

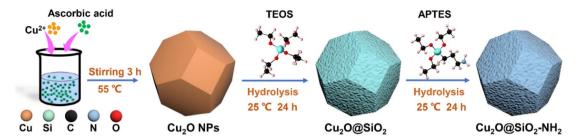


Fig. 1 The schematic illustration of the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> synthesis process.

and 74°, which belong to the (110), (111), (200), (220) and (311) crystal planes of Cu<sub>2</sub>O, respectively. However, the position of the diffraction peaks of Cu<sub>2</sub>O dodecahedron nanoparticles have no obvious change after SiO<sub>2</sub> coating and ¬NH<sub>2</sub> modification, indicating that the process of SiO<sub>2</sub> coating and ¬NH<sub>2</sub> modification have no significant effect on the crystal phase structure of Cu<sub>2</sub>O nanoparticles. The surface chemical state of the samples was characterized by X-ray photoelectron spectroscopy (XPS). As shown in Fig. 3b, for the Cu 2p XPS spectrum, there are only two

peaks at the binding energies of 932.3 and 952.0 eV for the Cu<sub>2</sub>O catalyst, which are ascribed to Cu<sup>+</sup> 2p<sub>3/2</sub> and 2p<sub>1/2</sub>, respectively. The Meanwhile for Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O-SiO<sub>2</sub>-NH<sub>2</sub> catalysts, a satellite peak at 943 eV appears in the Cu 2p XPS spectra, indicating the presence of Cu<sup>2+</sup> species. Meanwhile, the asymmetric peaks of Cu 2p can be deconvoluted into two sets of peaks. The first group of peaks with binding energies of 932.3 and 952.0 eV are attributed to 2p<sub>3/2</sub> and 2p<sub>1/2</sub> of Cu<sup>+</sup> species. The second set of peaks at 934.6 and 954.3 eV belong to 2p<sub>3/2</sub> and

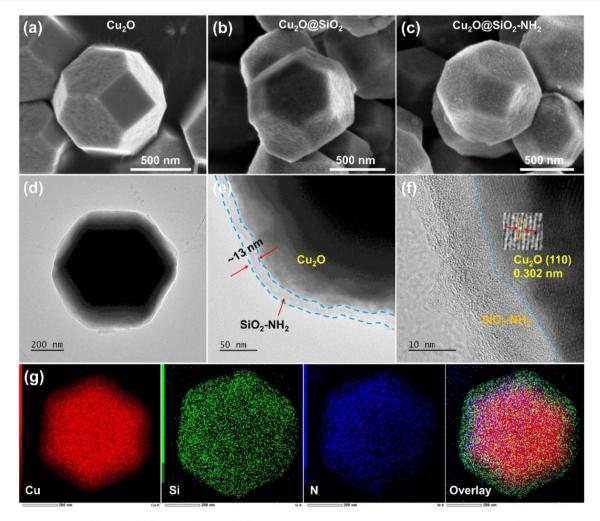


Fig. 2 The SEM images of (a)  $Cu_2O_0$  (b)  $Cu_2O_0SiO_2$ , and (c)  $Cu_2O_0SiO_2-NH_2$ ; and the structural characterization of  $Cu_2O_0SiO_2-NH_2$  (d and e) TEM images, (f) HR-TEM image and (g) EDX mapping.

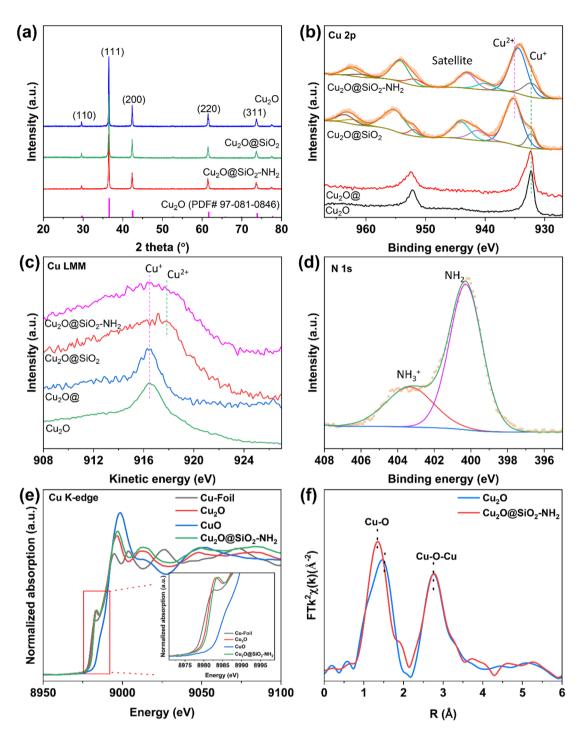


Fig. 3 Chemical composition characterization of Cu<sub>2</sub>O, Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub> -NH<sub>2</sub>. (a) XRD patterns, (b) Cu 2p XPS spectra, (c) Cu LMM XAES spectra, (d) N 1s XPS spectrum, (e) XANES spectra and (f) Fourier transformed EXAFS spectra of the Cu K-edge.

2p<sub>1/2</sub> of Cu<sup>2+</sup> species.<sup>29</sup> Compared with Cu<sub>2</sub>O, both Cu<sup>2+</sup> and Cu<sup>+</sup> species exist on the surface of Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub>, indicating strong interaction between SiO<sub>2</sub> and Cu species. This result is further confirmed by the Cu LMM X-ray induced Auger transition spectra (XAES) (Fig. 3c), where the Cu LMM XAES of Cu<sub>2</sub>O sample shows a symmetrical peak at 916.8 eV, which belongs to Cu<sup>+</sup> species, while the Cu LMM XAES of Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> show an asymmetric peak

with a wider full width at half maximum (FWHM), indicating the coexistence of Cu<sup>+</sup> and Cu<sup>2+</sup> species at 916.8 and 917.9 eV.<sup>30</sup> As is well known, XRD is the analysis of the entire bulk phase, while XPS is surface analysis. No CuO phase is observed in the XRD pattern (Fig. 3a), indicating a low content of Cu<sup>2+</sup>. XPS spectra (Fig. 3b) show a clear Cu<sup>2+</sup> peak, indicating that Cu<sup>2+</sup> is mainly present on the surface, while for Cu2O@SiO2-NH2 and Cu2O@SiO2 catalysts, it is at the interface between Cu2O and

SiO<sub>2</sub>. The production of Cu<sup>2+</sup> indicates that the strong interaction between SiO2 and Cu2O at the interface induces the oxidation effect of low valent Cu, which will affect the reduction of Cu<sub>2</sub>O in the CO<sub>2</sub>RR.<sup>31</sup> Moreover, XPS analysis was also performed on the Cu<sub>2</sub>O(a) sample that was treated under the same conditions without TEOS and APTES, and there is no significant difference in Cu 2p XPS between the Cu<sub>2</sub>O(a) and Cu<sub>2</sub>O samples, which indicates that the treatment process did not oxidize Cu<sup>+</sup> to Cu<sup>2+</sup>. Therefore, it can be confirmed that the strong interaction between SiO2 and Cu species at the Cu2O-SiO2 interface promotes the formation of Cu<sup>2+</sup> species. In addition, the chemical state of the -NH2 group on the surface was characterized by N 1s XPS. As shown in Fig. 3d, the spectrum of N 1s XPS can be divided into two peaks located at the binding energies of 400 and 403.2 eV, respectively. According to a previous report, N 1s XPS at low binding energy belongs to the -NH<sub>2</sub> group, while the peak at high binding energy belongs to -NH<sub>3</sub><sup>+</sup>. <sup>32</sup> This means that part of the -NH<sub>2</sub> group on Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> has been protonated, which may increase the local pH on the catalyst surface.22

To explore more detailed structural information, the samples are further investigated by X-ray absorption fine structure spectroscopy (XAFS). Fig. 3e shows the X-ray absorption near-edge structure (XANES) spectra of Cu. In the Cu Kedge spectra, the pre-edge peak at 8987 eV is attributed to the dipole-forbidden 1s to 3d electron transition, which represents the fingerprint of Cu<sup>2+</sup>. Moreover, the absorption edge of the curve located between those for Cu2O and CuO shows the averaged valence state of Cu species in Cu2O@SiO2-NH2 between +1 and +2, which is consistent with XPS data. Moreover, the extended X-ray absorption fine structure (EXAFS) spectra of the Cu K-edge show that compared to pure Cu<sub>2</sub>O, the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst exhibits a shorter Cu-O bond length in the first shell, indicating that SiO2 enhances the bonding between Cu<sup>2+</sup>/Cu<sup>+</sup> and O (Fig. 3f). To demonstrate the interaction between -NH2 groups and CO2, the CO2 adsorption capacity of the catalyst was tested. As shown in Fig. S6,† compared to Cu<sub>2</sub>O@SiO<sub>2</sub>, Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> exhibits stronger CO<sub>2</sub> adsorption, indicating that the modification of -NH<sub>2</sub> significantly enhances the CO<sub>2</sub> adsorption capacity, which will play an important role in promoting the activity of the CO<sub>2</sub>RR.

## 3.2 Electrochemical CO<sub>2</sub> reduction performance

The catalytic performance of  $Cu_2O@SiO_2-NH_2$  for the  $CO_2RR$  was evaluated in a flow-cell with 1 M KCl cathode electrolyte (Fig. S7†). The gas and liquid phase products were detected by online gas chromatography (GC) and  $^1H$  nuclear magnetic resonance ( $^1H$  NMR), respectively, (Fig. S8 and S9†). Fig. 4a shows the linear sweep voltammetry (LSV) curves of  $Cu_2-O@SiO_2-NH_2$  and the control samples. The cathode current density increases sharply after  $CO_2$  gas is introduced, corresponding to the catalytic  $CO_2RR$ . When  $CO_2$  is replaced by  $N_2$ , the cathodic current of  $Cu_2O@SiO_2-NH_2$  decreases significantly, which indirectly indicates the low HER activity of  $Cu_2-O@SiO_2-NH_2$ . Under a  $N_2$  atmosphere, the HER current density of the  $Cu_2O@SiO_2-NH_2$  catalyst is relatively low compared to

 ${\rm Cu_2O}$ . Another possible reason is that the modification of  ${\rm SiO_2}$  and  ${\rm -NH_2}$  groups hinders the diffusion of  ${\rm H_2O}$  molecules to the catalyst surface, while the  ${\rm CO_2}$  atmosphere eliminates this obstacle and accelerates the adsorption and diffusion of  ${\rm H_2O}$  and  ${\rm CO_2}$ . The current density of the  ${\rm CO_2RR}$  on  ${\rm Cu_2O@SiO_2-NH_2}$  is significantly higher than that on  ${\rm Cu_2O}$  and  ${\rm Cu_2O@SiO_2}$ , suggesting that  ${\rm Cu_2O@SiO_2-NH_2}$  has a strong  ${\rm CO_2RR}$  activity. Due to the exposure of the  ${\rm Cu_2O}$  catalyst to the electrolyte solution, its HER current density under the  ${\rm N_2}$  atmosphere is slightly higher than that of  ${\rm Cu_2O@SiO_2}$  and  ${\rm Cu_2O@SiO_2-NH_2}$ , indicating that the HER is more likely to occur in the  ${\rm Cu_2O}$  catalyst.

The product distribution of the CO<sub>2</sub>RR over Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and the control samples in the cathode potential range of -1.1 to -1.9 V as shown in Fig. 4b-d. The total FE of  $C_{2+}$ products exhibits a volcanic trend relative to the cathodic potential change over Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> (Fig. 4b), and the total current density increases from 80 to 375 mA cm<sup>-2</sup> (Fig. S10†). Under a current density of 292 mA cm<sup>-2</sup> at -1.7 V, the FE of  $C_{2+}$ products reaches the highest value of 81.2% (including C<sub>2</sub>H<sub>4</sub>: 40.2%, C<sub>2</sub>H<sub>5</sub>OH: 29%, CH<sub>3</sub>COOH: 9%, and C<sub>3</sub>H<sub>7</sub>OH: 3%), which has a higher activity than most reported catalysts (Table S1†). The FE of H<sub>2</sub> and C<sub>1</sub> is only 12% and 6%, respectively. In comparison, the FE of  $C_{2+}$  is 68.3% ( $C_2H_4$ : 35%,  $C_2H_5OH$ : 24.3%, CH<sub>3</sub>COOH: 6.5%, and C<sub>3</sub>H<sub>7</sub>OH: 2.5%) over Cu<sub>2</sub>O@SiO<sub>2</sub> at -1.7 V (Fig. 4c). Meanwhile for Cu<sub>2</sub>O dodecahedron nanoparticles, the  $C_{2+}$  FE of  $Cu_2O$  is only 61.7% ( $C_2H_4$ : 31%,  $C_2H_5OH$ : 21%, CH<sub>3</sub>COOH: 7%, and C<sub>3</sub>H<sub>7</sub>OH: 2.7%) at the optimum potential of -1.6 V (Fig. 4d). As a result, the ratio of  $C_{2+}/C_1$ increases significantly from 4 in Cu<sub>2</sub>O to 13.5 in Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> (Fig. S11a†). In addition, the partial current densities of C<sub>2+</sub> products of different samples increase from 147 mA cm<sup>-2</sup> of Cu<sub>2</sub>O to 168 mA cm<sup>-2</sup> of Cu<sub>2</sub>O@SiO<sub>2</sub> during the CO<sub>2</sub>RR process, and then it further increases to 237 mA cm<sup>-2</sup> over Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> (Fig. 4e and S11b-d†). These results indicate that the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst has a high selectivity of C<sub>2+</sub> products in the process of the CO<sub>2</sub>RR.

By comparison, it can be found that when Cu<sub>2</sub>O nanoparticles are coated with SiO2, the HER is inhibited and the selectivity of C<sub>2+</sub> products increases in the full cathodic potential range. This indicates that the SiO<sub>2</sub> coating layer helps to promote the C-C coupling process. According to the Cu 2p XPS results, the Cu species on the surface will maintain a high valence state after coating with SiO2, thus improving the adsorption strength of \*CO on Cu species and increasing the surface coverage of \*CO,33 followed by enhanced C-C coupling. After modifying the surface of the Cu<sub>2</sub>O@SiO<sub>2</sub> sample with the -NH<sub>2</sub> group, the CO selectivity increases at low cathodic potential, indicating that the CO<sub>2</sub>RR process is accelerated. According to previous reports, the interaction between nucleophilic N in -NH<sub>2</sub> and electrophilic C in CO<sub>2</sub> molecules can enrich CO<sub>2</sub>, thus increasing the local CO2 concentration on the catalyst surface, 22,34,35 and increasing the conversion rate of CO<sub>2</sub> to CO. Therefore, the reaction environment with a high local concentration of \*CO can be provided at higher cathodic potential. Meanwhile, according to the N 1s XPS results (Fig. 3d), part of the -NH<sub>2</sub> group on the catalyst surface interacts with H<sub>2</sub>O to

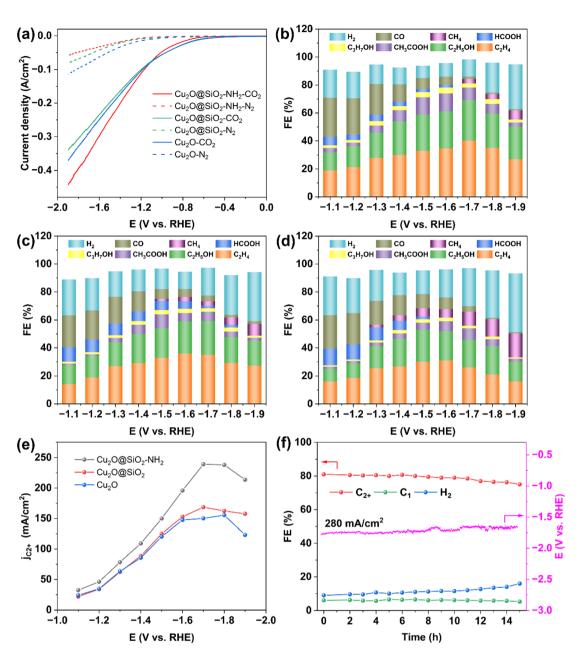


Fig. 4 CO<sub>2</sub>RR performance on Cu<sub>2</sub>O@SiO<sub>2</sub> – NH<sub>2</sub>, Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O catalysts. (a) LSV curves toward the CO<sub>2</sub>RR; product distributions and corresponding faradaic efficiencies produced by Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> (b), Cu<sub>2</sub>O@SiO<sub>2</sub> (c), and Cu<sub>2</sub>O (d), (e) the partial current density of C<sub>2+</sub> products, and (f) stability test of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> at 280 mA cm<sup>-2</sup> in 1 M KCl electrolyte.

form protonated -NH<sub>3</sub><sup>+</sup> and release OH<sup>-</sup> at the same time, leading to a higher local pH value of the reaction micro-environment,22 which is beneficial to promote the dimerization process of the C<sub>1</sub> intermediate.<sup>36</sup> Therefore, the positively charged Cu species coupled with the reaction microenvironment with sufficient CO supply and a high local pH value created by the surface -NH2 group significantly enhance the formation of C<sub>2+</sub> products from the CO<sub>2</sub>RR and increase the FE of C<sub>2+</sub> to 81.2% (Fig. 4b). However, in the Cu<sub>2</sub>O catalyst without SiO<sub>2</sub> coating, the FE of CH<sub>4</sub> increases at high potential (Fig. 4d). According to a previous report, the CO<sub>2</sub>RR is conducive to the formation of the C<sub>1</sub> product over the bulk Cu catalyst in neutral electrolyte. 37,38 Therefore, it can be inferred that Cu<sub>2</sub>O is rapidly reduced to form Cu in the reaction process, which leads to the formation of CH<sub>4</sub> and promotes the HER process at the same time, while the  $SiO_2$  coating promotes the formation of  $C_{2+}$  by stabilizing the positively charged Cu species in the catalyst.31 To eliminate the influence of the Cu/PTFE substrate on the analysis results, the CO<sub>2</sub>RR performance of the Cu/PTFE substrate was tested under the same conditions. It is found that the CO<sub>2</sub>RR to C2+ product conversion over Cu/PTFE shows a maximum FE of 26.2% at -1.5 V, and the FE of H<sub>2</sub> reaches 58% with a total current density of only 67 mA cm<sup>-2</sup> (Fig. S12†). The partial current density of C2+ products over Cu/PTFE is only 17 mA

cm $^{-2}$ , compared to 237 mA cm $^{-2}$  over Cu $_2$ O@SiO $_2$ -NH $_2$ , which shows that the main activity source of the CO $_2$ RR to C $_{2+}$  products is originated from the target catalyst, and the Cu/PTFE substrate has little effect on the activity of the catalysts. The pH value of the electrolyte was also tested during the CO $_2$ RR. Due to the generation of OH $^-$  at the cathode and the reaction of some OH $^-$  with CO $_2$  to generate CO $_3$ <sup>2 $^-$ </sup>, the pH increased from 6.82 at 0 V to 10.11 at -1.9 V (Fig. S13 $^+$ ), and the local alkaline environment may facilitate C–C coupling. $^2$  In addition to the excellent FE of C $_2$ +, Cu $_2$ O@SiO $_2$ -NH $_2$  also exhibits high stability at high current densities. The FE of C $_2$ + from the CO $_2$ RR over Cu $_2$ O@SiO $_2$ -NH $_2$  does not decrease significantly for 15 h with 280 mA cm $^{-2}$  current density in 1 M KCl electrolyte and remains above 75% (Fig. 4f).

## 3.3 Characterization of the samples after the activity test

Considering the reconstruction phenomenon of the oxidation state Cu-based catalyst during the CO<sub>2</sub>RR, it is necessary to further explore the activity source of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and the control samples, so the structure and composition of the samples after the activity test were characterized (the samples after the test were stored in a vacuum). As shown in TEM images of Fig. S14-S16,† the morphologies of Cu2O@SiO2-NH2 and Cu<sub>2</sub>O@SiO<sub>2</sub> catalysts have no obvious change after the CO<sub>2</sub>RR, except that the thickness of the SiO2-NH2 layer slightly decreases, indicating that the coating layer is partially dissolved during the reaction. It can be explained by the fact that the formation of OH during the CO2RR increases the pH of the solution, and SiO<sub>2</sub> reacts with OH<sup>-</sup> leading to a decrease in the coating layer thickness. Meanwhile, the HR-TEM images of Cu2O@SiO2-NH2 and Cu2O@SiO2 samples (Fig. S14c, d and S15c,  $d\dagger$ ) show lattice fringes of d = 0.302, 0.213 and 0.209 nm, which belong to the (110) and (200) of Cu<sub>2</sub>O and Cu (111) crystal facets, respectively. This indicates that the oxidation state Cu on the catalyst surface is partially reduced, forming the Cu-Cu<sub>2</sub>O interface; therefore, the metal-oxide interface effect can effectively improve the formation rate of C<sub>2+</sub> from the CO<sub>2</sub>RR.<sup>20</sup> At the same time, the elements overlap each other in the EDX mapping of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub> samples, which proves that the Cu2O@SiO2-NH2 catalyst still maintains a complete coating structure after the CO<sub>2</sub>RR (Fig. S14e, f and S15e†). In contrast, the morphology of the Cu<sub>2</sub>O catalyst after the CO<sub>2</sub>RR is significantly changed (Fig. S16a and b†), and only the lattice fringe of the Cu (111) facet (d = 0.2086 nm) can be observed in the HR-TEM image (Fig. S16c†). This indicates that Cu<sub>2</sub>O nanoparticles are completely reduced to Cu during the CO<sub>2</sub>RR. Notably, irregular holes can be observed on the surface of Cu<sub>2</sub>O nanoparticles (Fig. S16d†), which further indicates that Cu<sub>2</sub>O nanoparticles are reduced, leading to a change in the morphology of nanoparticles. The EDX mapping also confirmed the morphology change (Fig. S16e†), where the Cu element is not evenly distributed. By comparing the TEM images of Cu<sub>2</sub>-O@SiO2-NH2, Cu2O@SiO2 and Cu2O catalysts, the results indicate that SiO<sub>2</sub> coating can stabilize the morphology of Cu<sub>2</sub>O nanoparticles, inhibit the reduction of oxidized Cu in the catalyst, and form a stable metal-oxide interface in the

reduction process, which accelerates the C-C coupling step during the CO<sub>2</sub>RR.

XRD characterization was carried out to analyze the chemical composition of the catalyst after the CO2RR. As shown in Fig. 5a, there is only one diffraction peak at  $2\theta = 43.2^{\circ}$  in the XRD pattern of the Cu<sub>2</sub>O catalyst, which is attributed to metal Cu (PDF# 97-004-3493), indicating that Cu<sub>2</sub>O is completely reduced during the CO<sub>2</sub>RR. There are two sets of diffraction peaks in the XRD patterns of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and Cu<sub>2</sub>O-SiO<sub>2</sub> catalysts, which are located at  $2\theta = 36.4^{\circ}$ ,  $42.5^{\circ}$  and  $2\theta = 43.2^{\circ}$ . They belong to the Cu<sub>2</sub>O (PDF# 97-018-0846) and Cu phases, respectively. The XRD results show that Cu<sub>2</sub>O nanoparticles coated with SiO2 inhibit the reduction of Cu+ species and form a metal-oxide interface in the CO2RR process. Combined with TEM characterization results, it is further demonstrated that SiO<sub>2</sub> coating is beneficial to stabilize the oxidized copper in Cu<sub>2</sub>O nanoparticles during the CO<sub>2</sub>RR, due to the strong interaction between SiO<sub>2</sub> and Cu<sub>2</sub>O species. At the same time, the Cu 2p XPS spectrum of Cu<sub>2</sub>O after the CO<sub>2</sub>RR (Fig. 5b) shows only two peaks located at 932.0 and 951.8 eV, belonging to Cu<sup>0</sup> species.39 Meanwhile for Cu 2p XPS of Cu2O@SiO2 and Cu2-O@SiO<sub>2</sub>-NH<sub>2</sub>, there is weak satellite peaks at 942-944 eV and acromial peaks at 934.7 eV, indicating the presence of a small amount of Cu2+ on the surface.40 We further analyzed the Cu LMM XAES spectra of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and control samples after the CO<sub>2</sub>RR. As shown in Fig. 5c, there is only one peak located at 918.1 eV in the Cu LMM XAES of the Cu<sub>2</sub>O catalyst, which belongs to Cu<sup>0</sup> species, suggesting that all Cu<sup>+</sup> species are reduced to Cu<sup>0</sup> species. In contrast, the Cu LMM XAES of Cu<sub>2</sub>-O@SiO<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalysts can be fitted into two peaks at 916.2 and 918.1 eV, belonging to the Cu<sup>+</sup> and Cu<sup>0</sup> species, respectively. 19,41 Compared with the Cu 2p XPS before the CO<sub>2</sub>RR (Fig. 3b), the surface of the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst is mainly Cu<sup>2+</sup>, and after the CO<sub>2</sub>RR, it is mainly mixed Cu<sup>+</sup> and Cu<sup>0</sup>, indicating that SiO<sub>2</sub> can stabilize part of Cu<sup>+</sup> and form Cu<sup>+</sup>-Cu<sup>0</sup> interfaces. The results are consistent with TEM and XRD images. Meanwhile, the Si 2p XPS also can be detected in Cu<sub>2</sub>-O@SiO2-NH2 and Cu2O@SiO2 catalysts, which confirms the presence of SiO2 on the catalyst surface after the CO2RR (Fig. S17†). Moreover, the N 1s XPS spectrum shows the retention of -NH<sub>2</sub> groups on the surface and the presence of groups in two states of -NH<sub>2</sub> and -NH<sub>3</sub><sup>+</sup>, indicating that the surface -NH<sub>2</sub> continued to play a role in the enrichment of CO<sub>2</sub> during the reaction process and accelerated the conversion rate of CO2 (Fig. 5d).

## 3.4 Reaction mechanism study

*In situ* Raman experiments were performed to study the valence changes of Cu species of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> and control samples, and to detect the key intermediates in the CO<sub>2</sub>RR process. As shown in Fig. 6, under open-circuit potential conditions, the two Raman peaks at 145 and 213 cm<sup>-1</sup> belong to the Cu<sub>2</sub>O phase.<sup>13</sup> When the cathodic potential is applied, the peaks of the Cu<sub>2</sub>O phase still exist in the Raman spectrum of Cu<sub>2</sub>-O@SiO<sub>2</sub>-NH<sub>2</sub>, indicating that the Cu<sup>δ+</sup> species can be well preserved in the CO<sub>2</sub>RR process. Similarly, this phenomenon

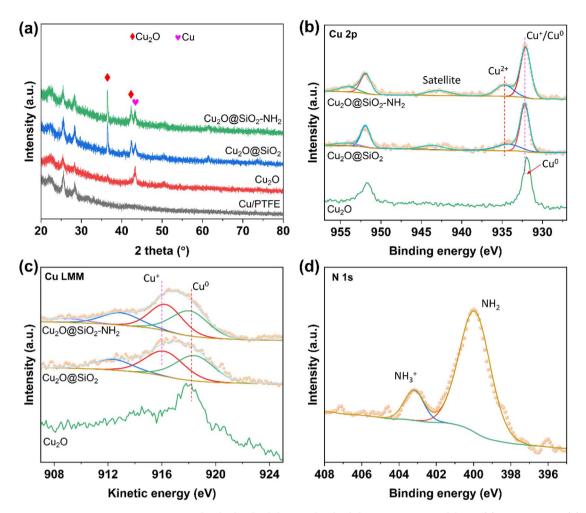


Fig. 5 Chemical composition characterizations of Cu<sub>2</sub>O, Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> after the CO<sub>2</sub>RR. (a) XRD patterns, (b) Cu 2p XPS spectra, (c) Cu LMM XAES spectra and (d) N 1s XPS spectrum.

has also been observed on the Cu<sub>2</sub>O@SiO<sub>2</sub> catalyst, where Cu<sub>2</sub>O species can exist stably with the increase of cathodic potential. In contrast, for the Cu<sub>2</sub>O catalyst, the two Raman peaks at 145 and 213 cm<sup>-1</sup> only can be observed under the open-circuit potential conditions. However, when a cathodic potential of -1.1 V is applied, the two peaks disappear, suggesting that the Cu<sub>2</sub>O on the catalyst surface is completely reduced to metal Cu. The above analysis results imply that the strong interaction between SiO<sub>2</sub> and Cu<sub>2</sub>O can improve the stability of Cu<sup>δ+</sup> species on the catalyst surface. This is consistent with the results of TEM and XRD of samples after the CO<sub>2</sub>RR. More importantly, in the Raman spectrum of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub>, an obvious peak at 529 cm<sup>-1</sup> is observed, which is related to the chemisorption of CO<sub>2</sub> on the copper surface (\*CO<sub>2ad</sub>), 42,43 and it further enhances with the increase of cathodic potential applied. This shows that the catalyst has strong CO<sub>2</sub> adsorption and activation ability (Fig. 6a). In contrast, the peak intensity of  ${^*CO}_{2ad}$  at 529 cm<sup>-1</sup> on Cu<sub>2</sub>O@SiO<sub>2</sub> and Cu<sub>2</sub>O catalysts decreases sharply (Fig. 6b and c), indicating that \*CO<sub>2ad</sub> is less adsorbed on the surface. Therefore, this result shows that -NH2 enhances the ability of the catalyst to adsorb and activate CO<sub>2</sub>. As mentioned above, the -NH<sub>2</sub> group can enrich CO<sub>2</sub> molecules, thus improving the CO<sub>2</sub> coverage on the catalyst surface.22

Moreover, the peaks at 297 and 373 cm<sup>-1</sup> are attributed to the rotation and stretching vibrations of \*CO on Cu (Cu-CO) in the Raman spectra, 12,44 which indicate the formation of CO and the adsorption of \*CO on the catalyst surface (Fig. 6a-c). At the same time, the most obvious peak at 2000-2080 cm<sup>-1</sup> is associated with \*CO<sub>a</sub> (Fig. 6d).27 It is worth noting that the adsorption peak of \*CO first increases and then decreases with the increase of cathodic potential, indicating that the coverage of \*CO on the catalyst surface increases first with the cathodic potential, which promotes the C-C coupling step. However, after the C-C coupling reaction, the \*CO adsorbed on the surface will be consumed, thus weakening the adsorption peak of \*CO.44 In contrast, the Cu-CO Raman signal on Cu<sub>2</sub>O@SiO<sub>2</sub> is weaker (Fig. 6b and e), indicating the low surface coverage of \*CO. Moreover, the Cu-CO Raman signal is the weakest on the Cu<sub>2</sub>O catalyst (Fig. 6c and f). The results of in situ Raman show that the interaction between -NH2 and CO2 creates a high local concentration of the CO<sub>2</sub> microenvironment at the Cu<sup>0</sup>-Cu<sup>+</sup>-NH<sub>2</sub> composite interfaces, which accelerates the activation of CO2 and generation of CO, and enhances the adsorption of

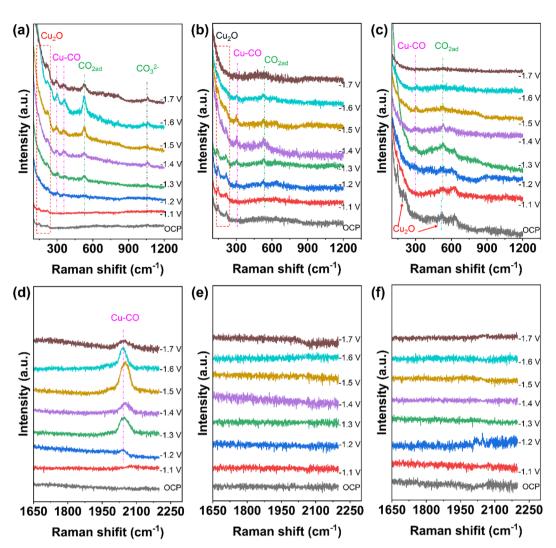


Fig. 6 In situ Raman spectra of the catalysts under  $CO_2RR$  conditions. (a and d)  $Cu_2O@SiO_2-NH_2$ , (b and e)  $Cu_2O@SiO_2$ , and (c and f)  $Cu_2O$ .

\*CO.<sup>45</sup> At the same time, the  $Cu^0/Cu^+$  synergistic effect at the interface may promote the C–C coupling step. However, the  $Cu^0-Cu^+$  interface without  $-NH_2$  on the  $Cu_2O@SiO_2$  surface leads to a low local concentration of the  $CO_2$  microenvironment, which suppresses the CO generation rate, followed by a slow C–C coupling step. The lack of a  $SiO_2$  coating layer on the  $Cu_2O$  catalyst leads to the quick reduction of  $Cu_2O$  to metal Cu, thus reducing the adsorption strength of CO.

In situ attenuated total reflectance-infrared absorption spectroscopy (ATR-IRAS) was carried out under CO₂RR conditions to monitor the adsorption intermediates and get insight into the CO₂RR mechanism more precisely. As shown in Fig. 7, when the applied cathodic potential is higher than −1.1 V, new infrared (IR) absorption peaks begin to appear in the ATR-IRAS of all catalysts. The most obvious peak appears at 1650 cm<sup>−1</sup> in the ATR-IRAS of Cu₂O@SiO₂-NH₂ and Cu₂O@SiO₂ (Fig. 7a, b), which is related to the IR absorption peak of H₂O.⁴6 The intensity of the IR absorption peak increases with the increase of cathodic potential, indicating that the process of H₂O adsorption and activation is accelerated at high cathodic

potential. In contrast, on the surface of the Cu2O catalyst, the intensity of this absorption peak decreases sharply. This suggests that the surface of Cu2O@SiO2 can promote the adsorption and activation of H2O. This can be explained by the fact that the metal-oxide interface (Cu<sup>0</sup>-Cu<sup>+</sup>) can regulate the dissociation process of H2O, resulting in high coverage of \*H species on the catalyst surface. 47,48 The presence of a metal-oxide interface is also confirmed by the XRD and TEM results. From the CO<sub>2</sub>RR equations in Table S2,† it can be seen that the CO<sub>2</sub>RR must involve the participation of active \*H, such as the transfer of 12 protons and 12 electrons to generate ethylene and ethanol, where the protons obtain electrons and become active \*H. Therefore, the peak intensity of the H<sub>2</sub>O peak represents the ability to activate H2O to produce active \*H, which is partially involved in the CO<sub>2</sub>RR and partially in the HER. For catalysts with high CO<sub>2</sub>RR activity, most of the active \*H is involved in the CO<sub>2</sub>RR. In contrast, for catalysts with poor CO<sub>2</sub>RR activity, most of the active \*H is involved in the HER. From Table S2,† it can also be seen that the number of electrons transferred is directly proportional to the number of protons consumed,

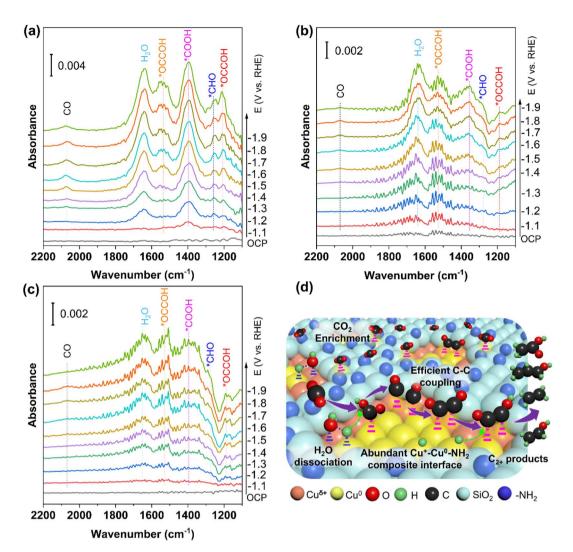


Fig. 7 In situ ATR-IRAS spectra of catalysts under CO<sub>2</sub>RR conditions and the reaction mechanism. (a) Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub>, (b) Cu<sub>2</sub>O@SiO<sub>2</sub>, and (c)  $Cu_2O$  and (d) reaction mechanism of the  $CO_2RR$  to  $C_{2+}$  product formation over the  $Cu_2O@SiO_2-NH_2$  catalyst.

which means that the number of active \*H is directly proportional to the current density. In Fig. S11,† the current density of C<sub>2+</sub> in the CO<sub>2</sub>RR process of the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst is 237 mA cm<sup>-2</sup>, and the current density of H<sub>2</sub> is only 35.32 mA cm<sup>-2</sup>, while for the Cu<sub>2</sub>O catalyst, the current density of C<sub>2+</sub> is only 147  $mA cm^{-2}$ , but the current density of  $H_2$  is 76.55  $mA cm^{-2}$ . From this result, it can be seen that more active \*H is generated in the Cu2O@SiO2-NH2 catalyst, and most of it is involved in the CO<sub>2</sub>RR. Although the HER current density of Cu<sub>2</sub>O is high, the total current density is low, resulting in less active \*H, which is consistent with the H<sub>2</sub>O peak intensity in the ATR-IRAS spectra.

In addition to the H2O absorption peak, the other strong peak located at 1390 cm<sup>-1</sup> belongs to the \*COOH species, 49 implying that the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> catalyst has strong adsorption and activation ability for CO2 molecules. The simultaneous adsorption and activation of H<sub>2</sub>O and CO<sub>2</sub> molecules indicate a good coupling between H<sub>2</sub>O dissociation and CO<sub>2</sub> reduction. The activated \*CO<sub>2</sub> species and surface \*H<sub>ad</sub> species promote the formation of \*CO species, which can be confirmed by the

\*CO absorption peak appearing around 2070 cm<sup>-1</sup> in the ATR-IRAS spectrum.46 There is an obvious \*CO IR absorption peak on the Cu2O@SiO2-NH2 surface, indicating the high coverage of \*CO on the Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> surface, which promotes the formation of C<sub>2+</sub> products (Fig. 7a). In contrast, the ATR-IRAS of Cu2O@SiO2 shows a weak \*CO IR absorption peak, which corresponds to a low CO coverage (Fig. 7b). However, no obvious IR absorption peak of \*CO was found on the surface of Cu<sub>2</sub>O, indicating weak \*CO adsorption capacity on the surface, because Cu<sub>2</sub>O was reduced to Cu<sup>0</sup>, followed by low \*CO coverage (Fig. 7c). This finding proves that the presence of -NH<sub>2</sub> can improve the adsorption and activation of CO2 on the catalyst surface, and the Cu<sup>+</sup> species can promote the adsorption of CO, thus improving the surface coverage of \*CO.

In addition, the peaks of ATR-IRAS at 1260 cm<sup>-1</sup>, 1205 cm<sup>-1</sup> and 1530 cm<sup>-1</sup> are related to the intermediate species of \*CHO and \*OCCOH on the catalyst, respectively (Fig. 7).49 The absorption peak intensity of \*OCCOH increases with the cathodic potential, which is consistent with the enhancement

trend of the  $C_{2+}$  product formation rate with the change of the cathodic potential. Compared with  $Cu_2O@SiO_2$  and  $Cu_2O$  catalysts, the IR absorption peak of the  $C_2$  intermediate on  $Cu_2O@SiO_2$ – $NH_2$  is more intense, indicating that the  $C_2$  intermediate has a stable adsorption structure on the catalyst surface, which is conducive to promoting C–C coupling, followed by higher  $C_{2+}$  product selectivity. Therefore, on the surface of  $Cu_2O@SiO_2$ – $NH_2$ , the enhancement of the  $CO_2$  adsorption activation process improves the surface coverage of \*CO, thus accelerating the C–C coupling process. The high coverage of \*H\_{ad} species can enhance the protonation process of  $C_{2+}$  intermediates and desorption of products, thus promoting the efficient formation of  $C_{2+}$  products from the  $CO_2RR$  process.  $^{50,51}$ 

According to the above analysis results, the CO<sub>2</sub>RR mechanism on the surface of Cu<sub>2</sub>O@SiO<sub>2</sub>-NH<sub>2</sub> can be reasonably proposed (Fig. 7d). Firstly, CO<sub>2</sub> reaches the three-phase reaction interface through the gas diffusion layer, and then is enriched by -NH<sub>2</sub> at the Cu<sup>0</sup>-Cu<sup>+</sup>-NH<sub>2</sub> composite interfaces, forming a local microenvironment with a high concentration of CO<sub>2</sub>.34 CO<sub>2</sub> molecules diffused through the porous SiO<sub>2</sub> coating layer to reach the Cu<sup>0</sup>-Cu<sup>+</sup> interface, and adsorbed and activated at the active site to form \*CO<sub>2ad</sub>. At the same time, the H<sub>2</sub>O molecules are activated by the Cu<sup>0</sup>-Cu<sup>+</sup> interface to increase the concentration of \*H, which couples with CO2 activation to form \*COOH, and promotes the formation of \*CO. Then the Cu<sup>+</sup> enhances the adsorption of \*CO, which facilitate the C-C coupling process at the  $Cu^{\delta^+}/Cu^0$  interface. The  $C_2$  intermediate is protonated by \*H on the catalyst surface, which promotes product desorption and thus accelerates the formation of C2+ products. This mechanism is consistent with the theoretical calculation results reported in the literature. For example, the electron density around the C atoms in \*CO on the Cu<sub>2</sub>O-Cu interface is higher than that on Cu2O, which reduces the reaction energy barrier of C-C coupling to form \*OCCO. Meanwhile, the energy barrier of H<sub>2</sub>O dissociation on Cu, Cu<sub>2</sub>O, and Cu<sub>2</sub>O-Cu is 2.33, 2.15, and 1.64 eV, respectively; therefore, the faster H<sub>2</sub>O dissociation and promoted C-C coupling contribute to accelerated C2+ product formation from the CO2RR on the Cu<sub>2</sub>O-Cu interface.48

## 4. Conclusion

In this work, dodecahedral  $Cu_2O@SiO_2-NH_2$  nanoparticles have been synthesized by hydrolysis of TEOS and APTES on the surface of  $Cu_2O$  particles for the  $CO_2RR$  to  $C_{2+}$  products. A series of characterization results show electronic interaction between  $Cu_2O$  and  $SiO_2-NH_2$ , and the  $Cu^0-Cu^+-NH_2$  composite interface is formed in the  $CO_2RR$  process. With the help of the interface effect, the FE of  $C_{2+}$  products reaches 81.3% with a current density of 290 mA cm $^{-2}$ , and is stable for 15 h without significant degradation of activity. Combined with XPS and *in situ* Raman spectroscopy, the high activity and stability originate from the interaction between  $SiO_2$  and  $Cu_2O$ , which stabilizes the positively charged Cu species and creates a stable  $Cu^0-Cu^+$  interface under  $CO_2RR$  conditions. Meanwhile, the surface –  $NH_2$  can enrich  $CO_2$  and promote the adsorption and activation

of  $CO_2$  on the catalyst surface, which accelerates the formation of \* $CO_2$ ; the  $-NH_2$  protonation process increases the local pH, which creates a reaction microenvironment that facilitates C–C coupling at the  $Cu^0$ – $Cu^+$ – $NH_2$  composite interface, and improves the efficiency of the  $CO_2RR$  to  $C_2$ +. This research provides a new idea for the surface modification of Cu-based catalysts and the design of an efficient  $Cu^0$ – $Cu^+$ – $NH_2$  composite interface.

## **Author contributions**

Conceptualization: Z.-L. W.; methodology: Z.-Y. Z. and H. T.; software: H. T.; validation: Z.-Y. Z. and H. J.; formal analysis: X. W., L. B., and Y. L.; investigation: Y. L. and N. K.; resources: Z.-L. W.; data curation: all authors; writing – original draft: all authors; writing – review & editing: all authors; visualization: Z.-Y. Z. and Z.-L. W.; supervision: Y. Y. and Z.-L. W.; project administration: Y. Y. and Z.-L. W.; funding acquisition: N. K., Y. Y., and Z.-L. W.

## Conflicts of interest

There are no conflicts to declare.

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